14.0-30.0 GHz GaAs MMIC Buffer Amplifier

February 2007 - Rev 05-Feb-07

B1009-BD

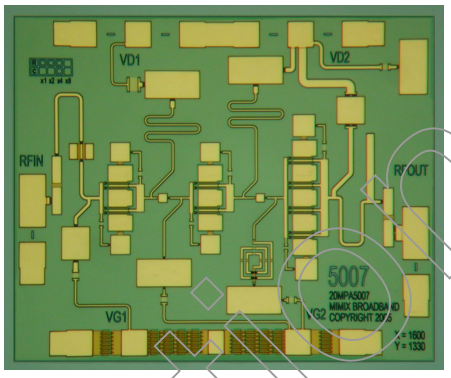
Features

- Excellent Transmit LO/Output Buffer Stage
- On-Chip ESD Protection
- 18.0 dB Small Signal Gain
- +22.0 dBm P1dB Compression Point
- 100% On-Wafer RF, DC and Output Power Testing
- 100% Visual Inspection to MIL-STD-883 Method 2010

General Description

Mimix Broadband's three stage 14.0-30.0 GHz GaAs MMIC buffer amplifier has a small signal gain of 18.0 dB with a +22.0 dBm P1dB output compression point. This MMIC uses Mimix Broadband's 0.15 µm GaAs PHEMT device model technology, and is based upon electron beam lithography to ensure high repeatability and uniformity. The chip has surface passivation to protect and provide a rugged part with backside via holes and gold metallization to allow either a conductive epoxy or eutectic solder die attach process. This device is well suited for Millimeter-wave Point-to-Point Radio, LMDS, SATCOM and VSAT applications.

Chip Device Layout



Absolute Maximum Ratings

Supply Voltage (Vd)	+6.0 VDC
Supply Current (Id1,2)	110, 340 mA
Gate Bias Voltage (Vg)	+0.3 VDC
Input Power (Pin)	+12.0 dBm
Storage Temperature (Tstg)	-65 to +165 °C
Operating Temperature (Ta)	-55 to MTTF Graph[1]
Channel Temperature (Tch)	MTTF Graph[1]

(1) Channel temperature affects a device's MTTF. It is recommended to keep channel temperature as low as possible for maximum life.

Electrical Characteristics (Ambient Temperature T = 25 °C)

Parameter	Units	Min.	Typ.	Max.
Frequency Range (f)	GHz	14.0	-	30.0
Input Return Loss (S11)	dB	-	7.0	-
Output Return Loss (S22)	dB	-	8.0	-
Small Signal Gain (S21)	dB	-	18.0	-
Gain Flatness (ΔS21)	dB	-	+/-4.0	-
Reverse Isolation (S12)	dB	-	40.0	-
Output Power for 1dB Compression (P1dB)[2]	dBm	-	+22.0	-
Drain Bias Voltage (Vd1,2)	VDC	-	+5.0	+5.5
Gate Bias Voltage (Vg1,2)	VDC	-1.0	-0.6	0.0
Supply Current (Id1) (Vd=5.0V, Vg=-0.6V Typical)	mA	-	80	95
Supply Current (Id2) (Vd=5.0V, Vg=-0.6V Typical)	mA	-	240	290

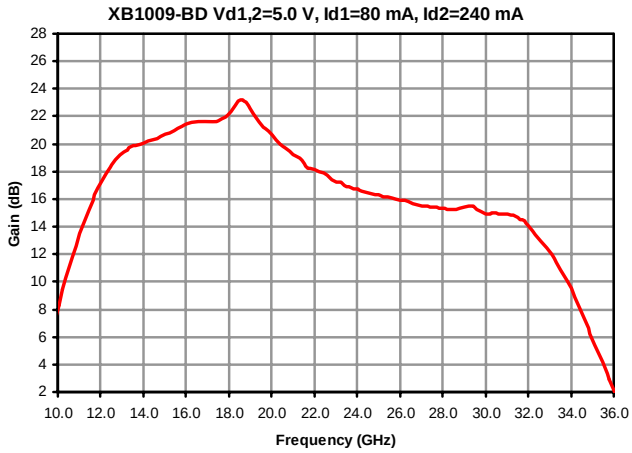
(2) Measured using constant current.

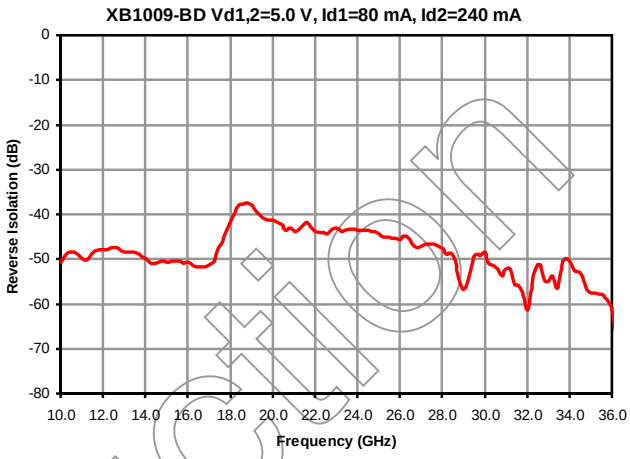
Pre-production

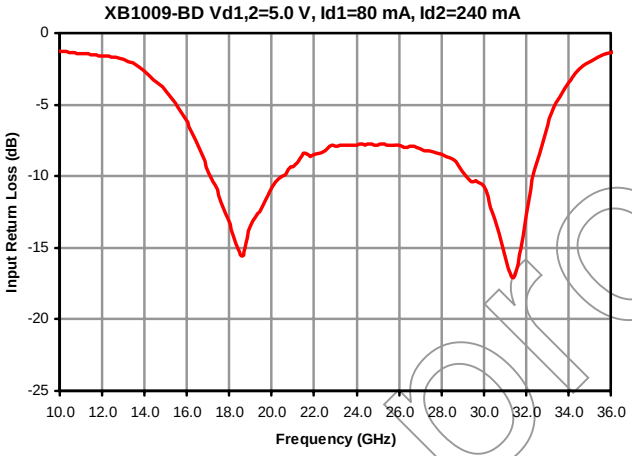
Mimix Broadband, Inc., 10795 Rockley Rd., Houston, Texas 77099
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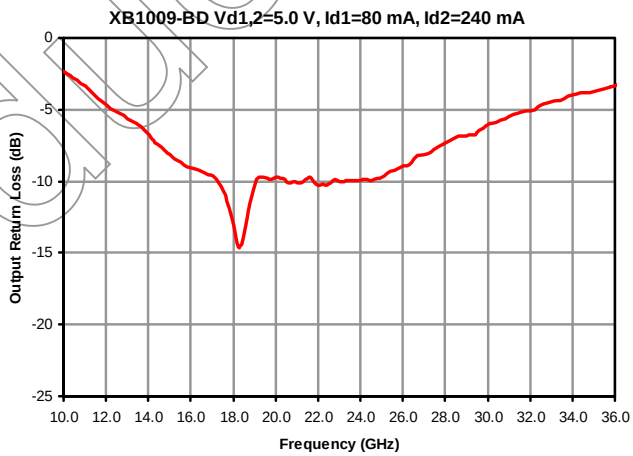
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Buffer Amplifier Measurements









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S-Parameters

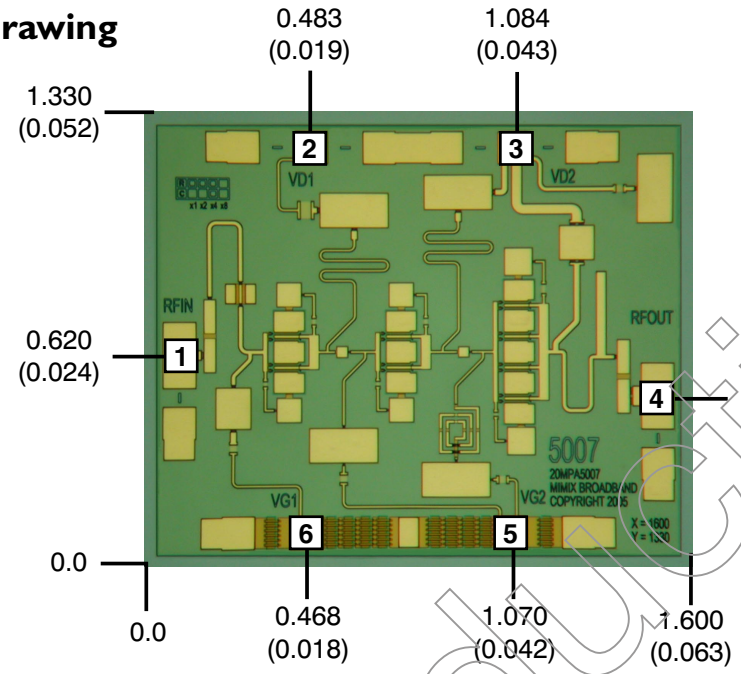
Typcial S-Parameter Data for XB1009-BD
Vd1,2=5.0 V, Id1=80 mA, Id2=240 mA

Frequency (GHz)	S11 (Mag)	S11 (Ang)	S21 (Mag)	S21 (Ang)	S12 (Mag)	S12 (Ang)	S22 (Mag)	S22 (Ang)
10.0	0.866	162.16	2.608	30.53	0.0030	-154.75	0.761	162.07
11.0	0.849	145.75	4.747	-30.65	0.0032	166.25	0.679	145.04
12.0	0.833	128.87	7.301	-89.65	0.0040	155.09	0.582	132.21
13.0	0.806	110.27	9.283	-147.04	0.0038	135.97	0.523	121.65
14.0	0.732	90.51	10.024	161.26	0.0032	123.06	0.458	109.87
15.0	0.624	71.60	10.809	118.79	0.0029	133.61	0.392	104.03
16.0	0.487	51.81	11.778	77.28	0.0029	135.74	0.352	100.26
17.0	0.327	33.04	12.072	36.18	0.0027	162.17	0.329	93.71
18.0	0.215	-8.09	12.912	1.81	0.0083	177.42	0.222	86.81
19.0	0.213	-167.70	13.450	-49.05	0.0126	112.53	0.309	115.45
20.0	0.291	144.90	10.757	-86.54	0.0085	93.17	0.326	100.62
21.0	0.340	128.44	9.159	-118.20	0.0065	89.01	0.313	96.01
22.0	0.376	116.95	8.069	-146.95	0.0065	81.94	0.308	92.99
23.0	0.401	107.20	7.259	-174.19	0.0070	78.23	0.314	91.37
24.0	0.405	101.42	6.847	159.58	0.0067	73.41	0.318	90.75
25.0	0.405	96.64	6.529	132.91	0.0062	60.44	0.326	92.39
26.0	0.407	91.85	6.226	105.85	0.0053	60.41	0.359	91.55
27.0	0.395	86.30	5.971	79.38	0.0044	57.95	0.393	88.92
28.0	0.378	82.93	5.821	52.32	0.0041	42.47	0.430	86.33
29.0	0.327	77.70	5.916	24.06	0.0014	56.44	0.456	80.22
30.0	0.292	76.71	5.560	-9.22	0.0038	58.26	0.497	78.77
31.0	0.168	90.04	5.565	-42.35	0.0024	61.77	0.532	73.51
32.0	0.231	150.73	5.054	-81.80	0.0008	92.87	0.558	68.12
33.0	0.479	145.59	4.050	-120.19	0.0018	97.43	0.597	63.18
34.0	0.670	131.41	2.985	-157.36	0.0030	90.04	0.634	57.91
35.0	0.793	117.57	1.957	170.20	0.0013	87.50	0.651	52.25
36.0	0.855	107.03	1.282	145.43	0.0009	91.57	0.682	47.79

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Mechanical Drawing

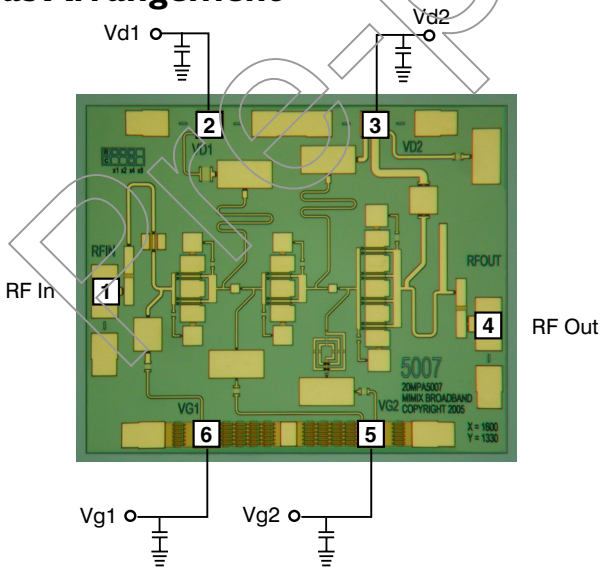


(Note: Engineering designator is 20MPA5007)

Units: millimeters (inches) Bond pad dimensions are shown to center of bond pad.
Thickness: 0.110 +/- 0.010 (0.0043 +/- 0.0004), Backside is ground, Bond Pad/Backside Metallization: Gold
All DC Bond Pads (except Vd3) are 0.100 x 0.100 (0.004 x 0.004). All RF Bond Pads (and Vd3) are 0.100 x 0.200 (0.004 x 0.008)
Bond pad centers are approximately 0.109 (0.004) from the edge of the chip.
Dicing tolerance: +/- 0.005 (+/- 0.0002). Approximate weight: 1.319 mg.

Bond Pad #1 (RF In)	Bond Pad #3 (Vd2)	Bond Pad #5 (Vg1)
Bond Pad #2 (Vd1)	Bond Pad #4 (RF Out)	Bond Pad #6 (Vg2)

Bias Arrangement



Bypass Capacitors - See App Note [2]

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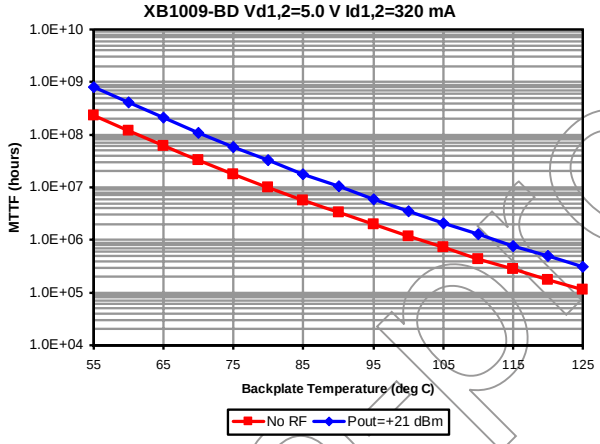
App Note [1] Biasing - It is recommended to separately bias each amplifier stage Vd1 through Vd2 at Vd(1,2)=5.0V with Id1=80 mA and Id2=240 mA. Separate biasing is recommended if the amplifier is to be used at high levels of saturation, where gate rectification will alter the effective gate control voltage. For non-critical applications it is possible to parallel all stages and adjust the common gate voltage for a total drain current Id(total)=320 mA. It is also recommended to use active biasing to keep the currents constant as the RF power and temperature vary; this gives the most reproducible results. Depending on the supply voltage available and the power dissipation constraints, the bias circuit may be a single transistor or a low power operational amplifier, with a low value resistor in series with the drain supply used to sense the current. The gate of the pHEMT is controlled to maintain correct drain current and thus drain voltage. The typical gate voltage needed to do this is -0.6V. Typically the gate is protected with Silicon diodes to limit the applied voltage. Also, make sure to sequence the applied voltage to ensure negative gate bias is available before applying the positive drain supply.

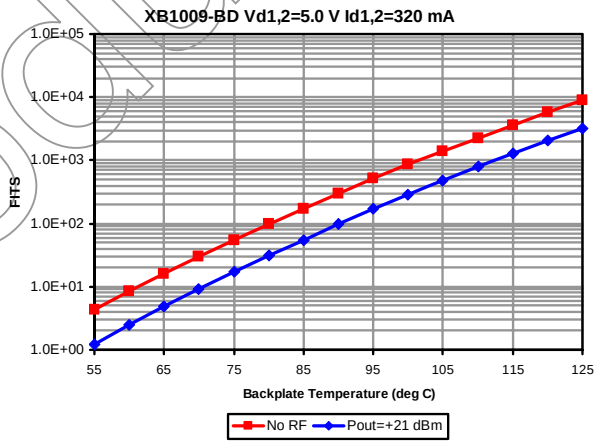
App Note [2] Bias Arrangement -
For Parallel Stage Bias (Recommended for general applications) -- The same as Individual Stage Bias but all the drain or gate pad DC bypass capacitors (~100-200 pF) can be combined. Additional DC bypass capacitance (~0.01 uF) is also recommended to all DC or combination (if gate or drains are tied together) of DC bias pads.

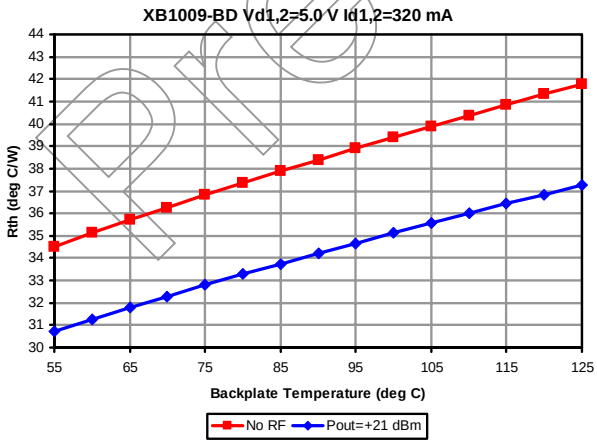
For Individual Stage Bias (Recommended for saturated applications) -- Each DC pad (Vd1,2 and Vg1,2) needs to have DC bypass capacitance (~100-200 pF) as close to the device as possible. Additional DC bypass capacitance (~0.01 uF) is also recommended.

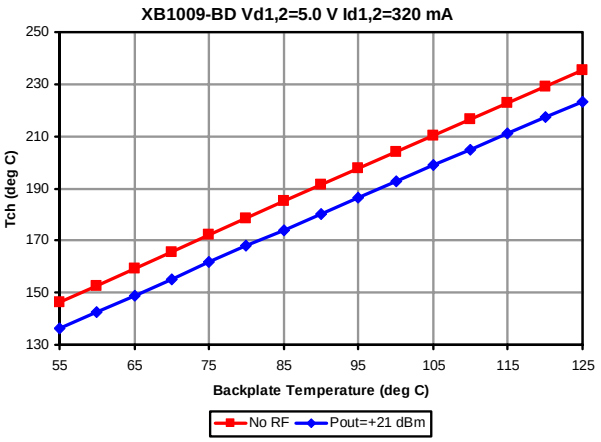
MTTF Graphs

These numbers were calculated based on accelerated life test information and thermal model analysis received from the fabricating foundry.





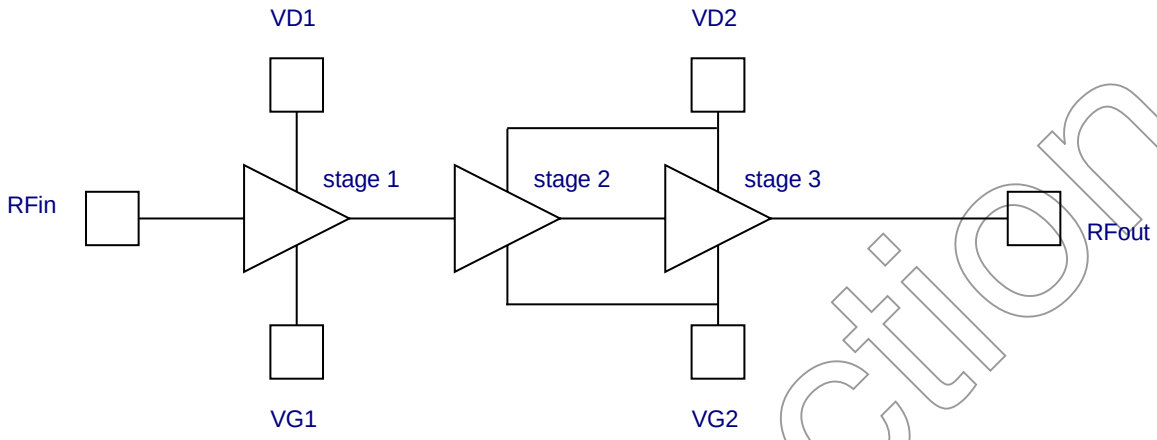




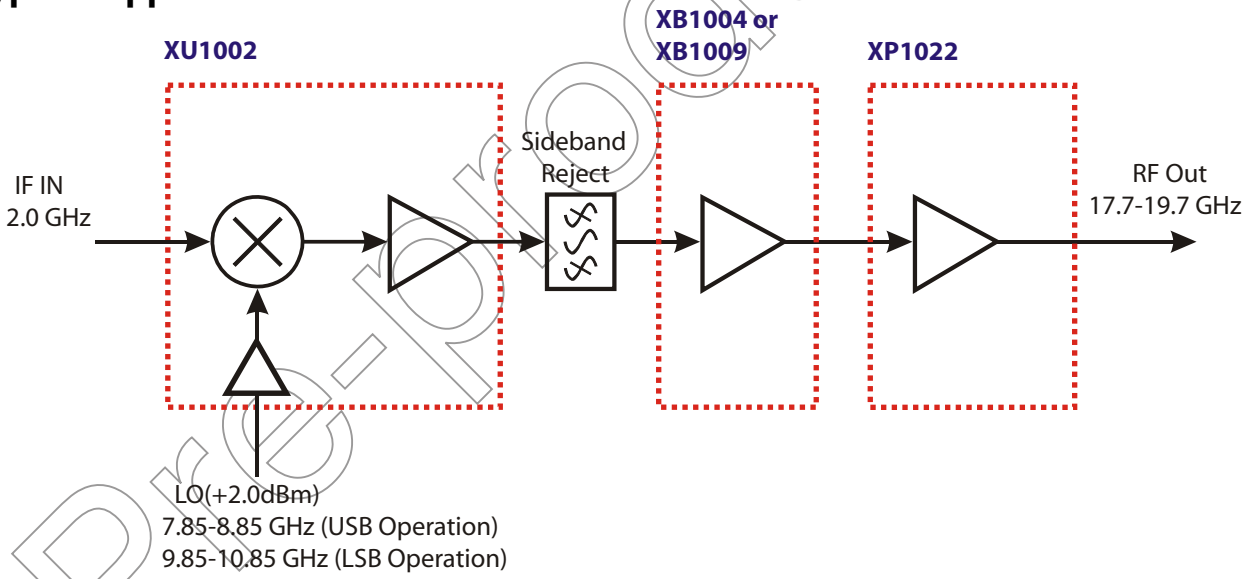
Preliminary Production

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Device Schematic



Typical Application



Mimix Broadband MMIC-based 18.0-25.0 GHz Transmitter Block Diagram

(Changing LO and IF frequencies as required allows design to operate as high as 25.0 GHz)

Mimix Broadband's 18.0-25.0 GHz XU1002 GaAs MMIC Transmitter can be used in saturated radio applications and linear modulation schemes up to 16 QAM. The transmitter can be used in upper and lower sideband applications from 18.0-25.0 GHz.

Pre-production

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Handling and Assembly Information

CAUTION! - Mimix Broadband MMIC Products contain gallium arsenide (GaAs) which can be hazardous to the human body and the environment. For safety, observe the following procedures:

- *Do not ingest.*
- *Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.*
- *Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.*

Life Support Policy - Mimix Broadband's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President and General Counsel of Mimix Broadband. As used herein: (1) Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user. (2) A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ESD - Gallium Arsenide (GaAs) devices are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic containers, which should be opened in cleanroom conditions at an appropriately grounded anti-static workstation. Devices need careful handling using correctly designed collets, vacuum pickups or, with care, sharp tweezers.

Die Attachment - GaAs Products from Mimix Broadband are 0.100 mm (0.004") thick and have vias through to the backside to enable grounding to the circuit. Microstrip substrates should be brought as close to the die as possible. The mounting surface should be clean and flat. If using conductive epoxy, recommended epoxies are Tanaka TS3332LD, Die Mat DM6030HK or DM6030HK-Pt cured in a nitrogen atmosphere per manufacturer's cure schedule. Apply epoxy sparingly to avoid getting any on to the top surface of the die. An epoxy fillet should be visible around the total die periphery. For additional information please see the Mimix "Epoxy Specifications for Bare Die" application note. If eutectic mounting is preferred, then a fluxless gold-tin (AuSn) preform, approximately 0.001 thick, placed between the die and the attachment surface should be used. A die bonder that utilizes a heated collet and provides scrubbing action to ensure total wetting to prevent void formation in a nitrogen atmosphere is recommended. The gold-tin eutectic (80% Au 20% Sn) has a melting point of approximately 280 °C (Note: Gold Germanium should be avoided). The work station temperature should be 310 °C +/- 10 °C. Exposure to these extreme temperatures should be kept to minimum. The collet should be heated, and the die pre-heated to avoid excessive thermal shock. Avoidance of air bridges and force impact are critical during placement.

Wire Bonding - Windows in the surface passivation above the bond pads are provided to allow wire bonding to the die's gold bond pads. The recommended wire bonding procedure uses 0.076 mm x 0.013 mm (0.003" x 0.0005") 99.99% pure gold ribbon with 0.5-2% elongation to minimize RF port bond inductance. Gold 0.025 mm (0.001") diameter wedge or ball bonds are acceptable for DC Bias connections. Aluminum wire should be avoided. Thermo-compression bonding is recommended though thermosonic bonding may be used providing the ultrasonic content of the bond is minimized. Bond force, time and ultrasonics are all critical parameters. Bonds should be made from the bond pads on the die to the package or substrate. All bonds should be as short as possible.

Part Number for Ordering	Description
XB1009-BD-000V	RoHS compliant die packed in vacuum release gel packs
XB1009-BD-EV1	XB1009-BD evaluation module

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